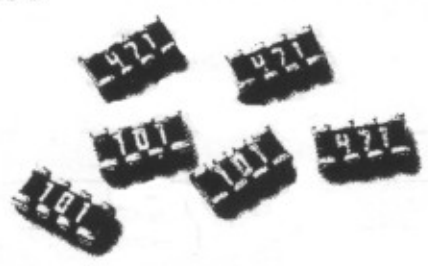
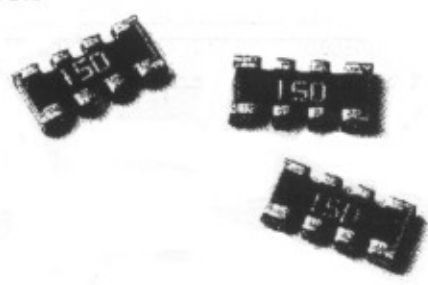


Thick Film Chip Resistors Array/YC Series (For 8Pin/4R)

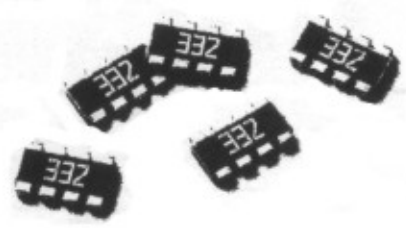
YC12



YC16



YC32

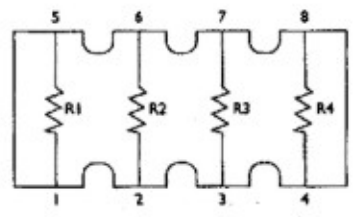


APPLICATIONS

Telecommunication Equipment Lap-Top and Note-Book Computer

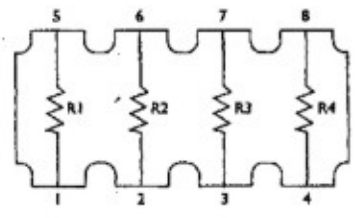
SCHEMATICS

YC12
YC16



R1=R2=R3=R4

YC32

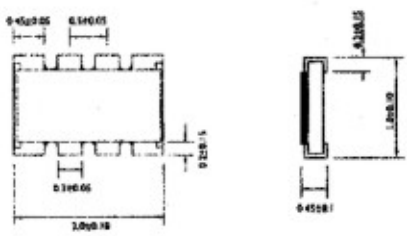


R1=R2=R3=R4

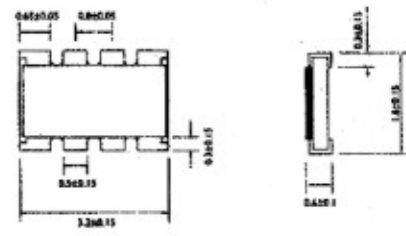
DIMENSIONS

Unit : mm

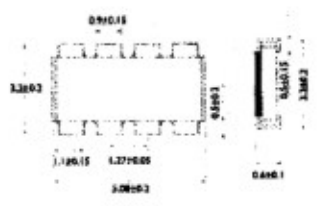
YC12



YC16



YC32



ELECTRICAL CHARACTERISTICS

STYLE	YC12	YC16	YC32
Power Rating at 70°C	1/16W	1/16W	1/8W
Operating Temp. Range	-55°C to +125°C		
Maximum Working Voltage	50V		200V
Maximum Overload Voltage	100V		400V
Dielectric Withstand Voltage	100V		500V
Number of Resistors	4		
Resistance Range	10Ω ~ 1MΩ		
Temperature Coefficient	±200ppm/°C		
Resistance Tolerance	±1%	±5%	

ELECTRICAL CHARACTERISTICS

PERFORMANCE TEST	TEST METHOD		APPRAISE
Temperature Coefficient	MIL-STD-202F, Method 304	LCT to UCT	by Type
Thermal Shock	MIL-STD-202F, Method 107G	25 Cycles, -65°C to +125°C (Step by Step 2min.)	±(1%+0.05Ω)
Low Temperature Operation	MIL-R-55342D, Para.4.7.4	One Hour at -65°C Followed by 45 Minutes RCWV	±(1%+0.05Ω)
Short Time Overload	MIL-R-55342D, Para.4.7.5	2.5 Times RCWV for 5 Seconds	±(2%+0.05Ω)
Insulation Resistance	JIS-C-5205, 5.6	RCOV for 1 Minute	>10GΩ
Dielectric Withstand Voltage	JIS-C-5205, 5.7	R.M.S. for 1 Minute	by Type
Resistance to Soldering Heat	MIL-STD-202F, Method 210C	Soldered to Test Board at 260°C for 10 Seconds	±(1%+0.05Ω)
Moisture Resistance	MIL-STD-202F, Method 106F	42Cycles.Total 1000 Hours	±(2%+0.05Ω)
Life	MIL-STD-202F, Method 108A	1000 Hours at 70°C RCWV Intermittent	±(3%+0.10Ω)
Solderability	JIS-C-5205, 6.11	230°C for 5 Seconds	>95% Coverage
Bending Strength	JIS-C-5202, 6.1.4	Unit Mounted in Center of 90mm Board Length, Deflected 1mm in Either Direction for 5 Seconds	±(1%+0.05Ω)